

Capabilities:

Capabilities: Reliable



2

Capabilities: Reliable



Capabilities: Reliable



2

Capabilities:

Fast



Capabilities:

Flexible



Capabilities:





Capabilities:

Heat Resistant



Capabilities:





Back to the Future

2001 SWTW presentation

Enabling X144 Wafer Sort

Roger Sinsheimer, P.E. Chief Engineer Xandex, Inc. Ken Karklin R&D Project Mgr. Agilent Technologies



Agilent Technologies Innovating the HP Way

http://www.swtest.org/swtw_library/2001proc/PDF/S6_04.pdf

Back to the Future

2001 SWTW presentation

V4400 Flash Memory Interface has 2304 I/O channels, 440mm diameter probe card.

Enabling X144 Wafer Sort

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Agilent Technologies Innovating the HP Way

http://www.swtest.org/swtw_library/2001proc/PDF/S6_04.pdf

Reliable





Back to the Future II

June 6, 2004

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2004 SWTW presentation

Adventures in Extreme Parallel Probing

Roger Sinsheimer, PE Chief Engineer



Roger Sinsheimer, PE

1

http://www.swtest.org/swtw_library/2004proc/PDF/S01_03_Sinsheimer.pdf

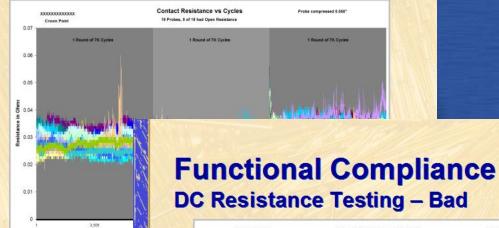
Back to the Future II, p2

The fundamental flaw in spring probes is the lack of force driving the plunger against the barrel



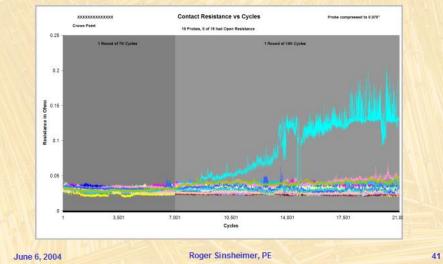
Back to the Future II, p3

Functional Compliance DC Resistance Testing – Good



The result of this inherent flaw is DC Resistance instability

June 6, 2004



Back to the Future II, p4

1600

1400 1200

> 800 600

400

200

0 0 0

uantity per bir 1000

June 6, 2004

Resistance histograms of various types of spring probes.

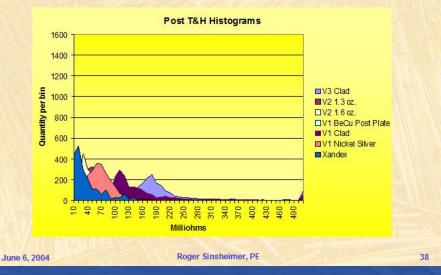
Functional Compliance DC Resistance Testing

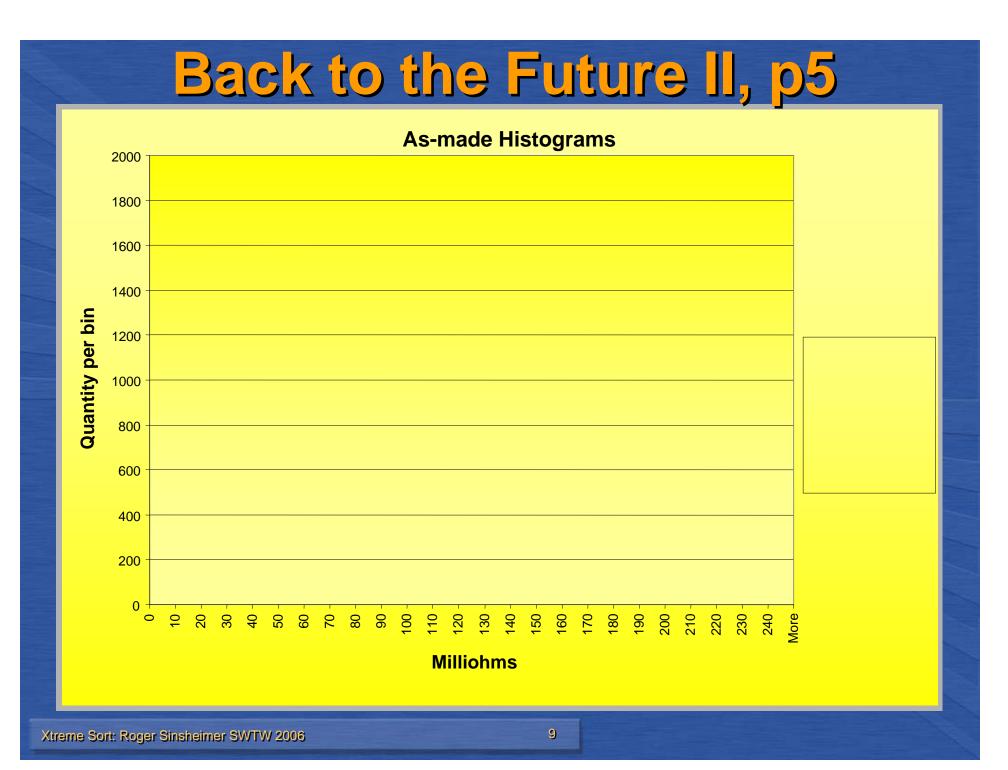
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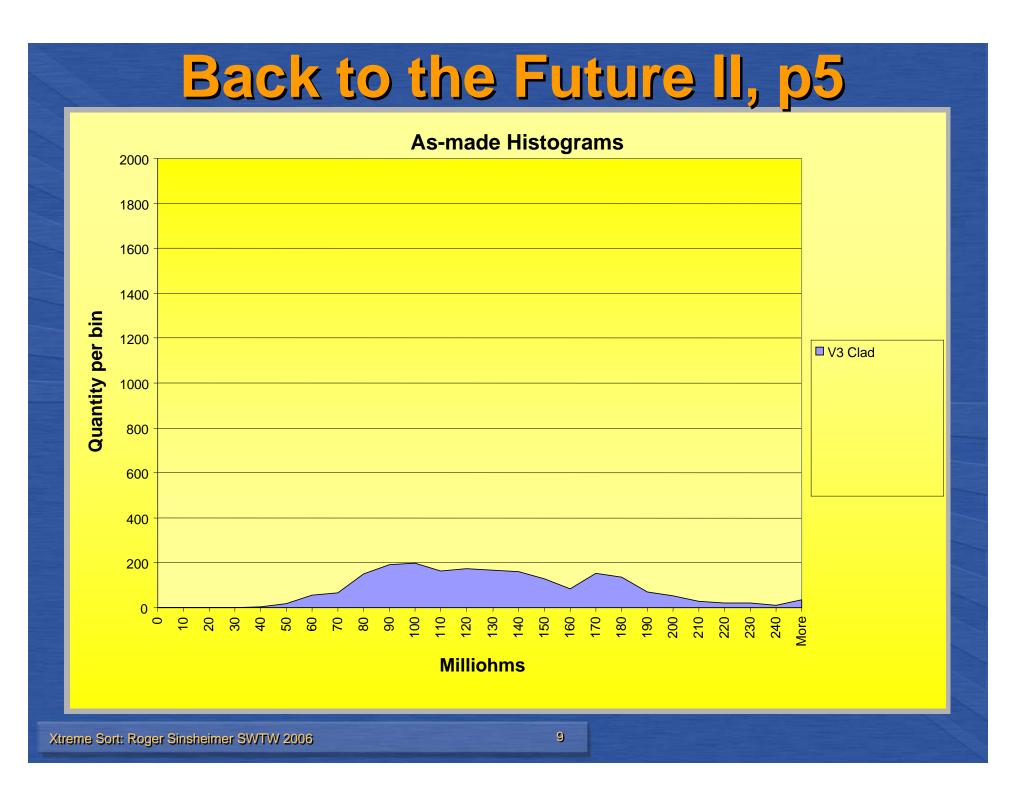
As-made Histograms

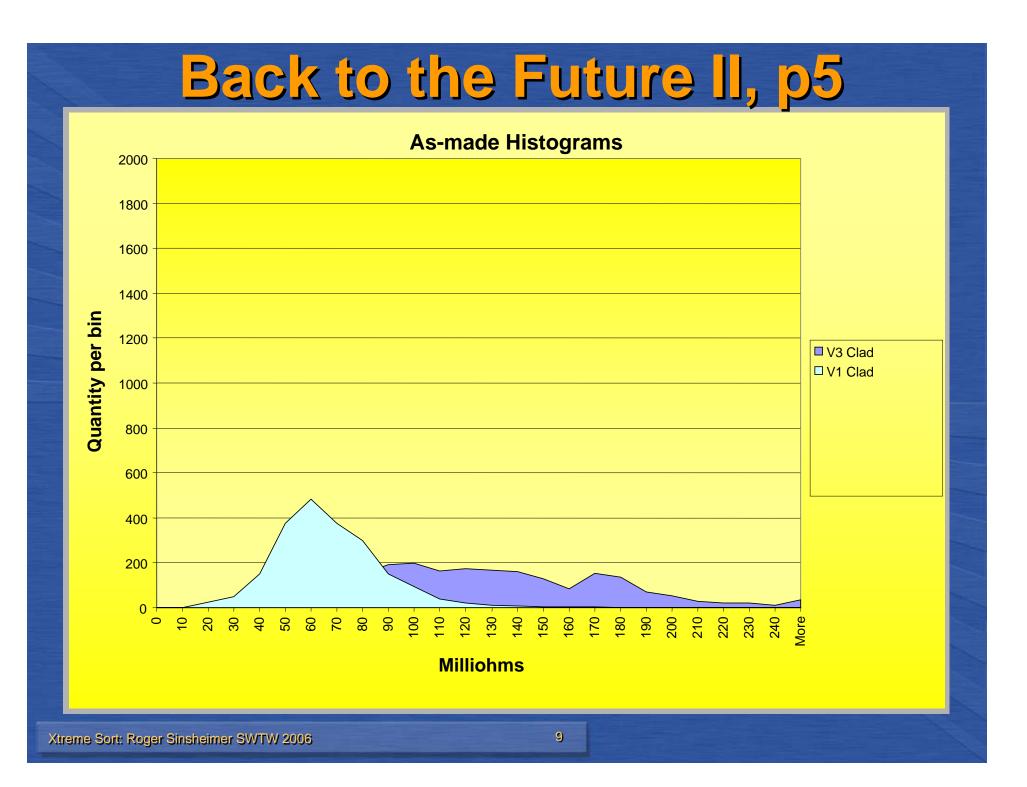
Functional Compliance DC Resistance Testing

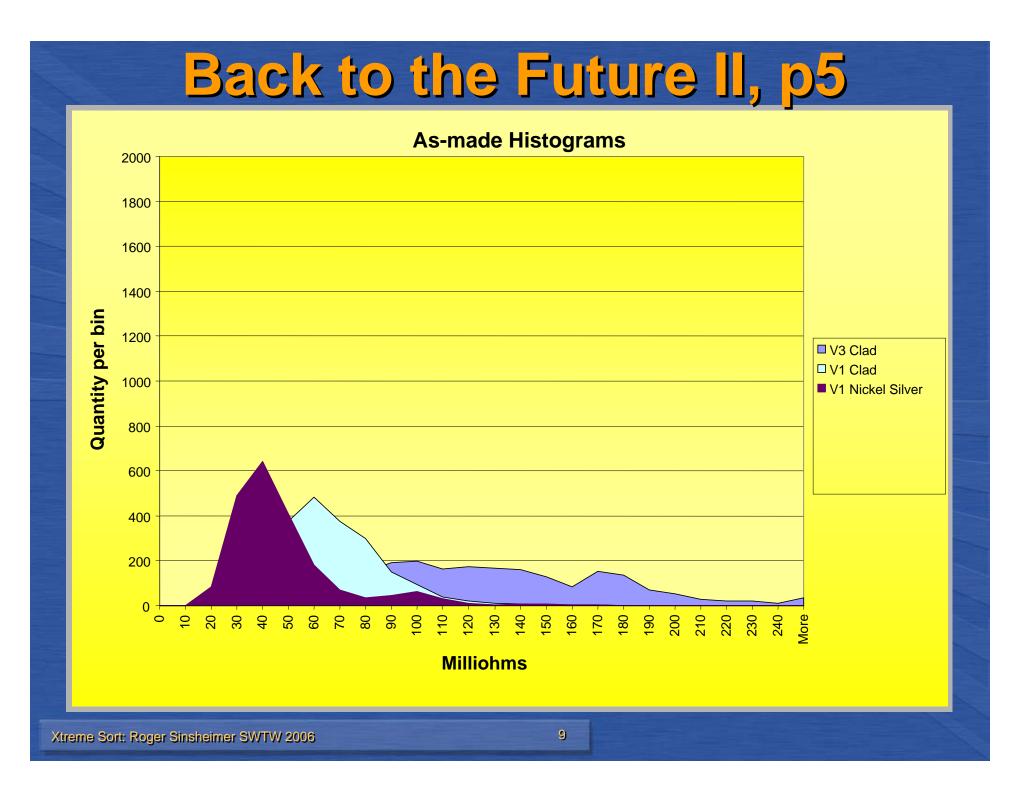
DV3 Clad

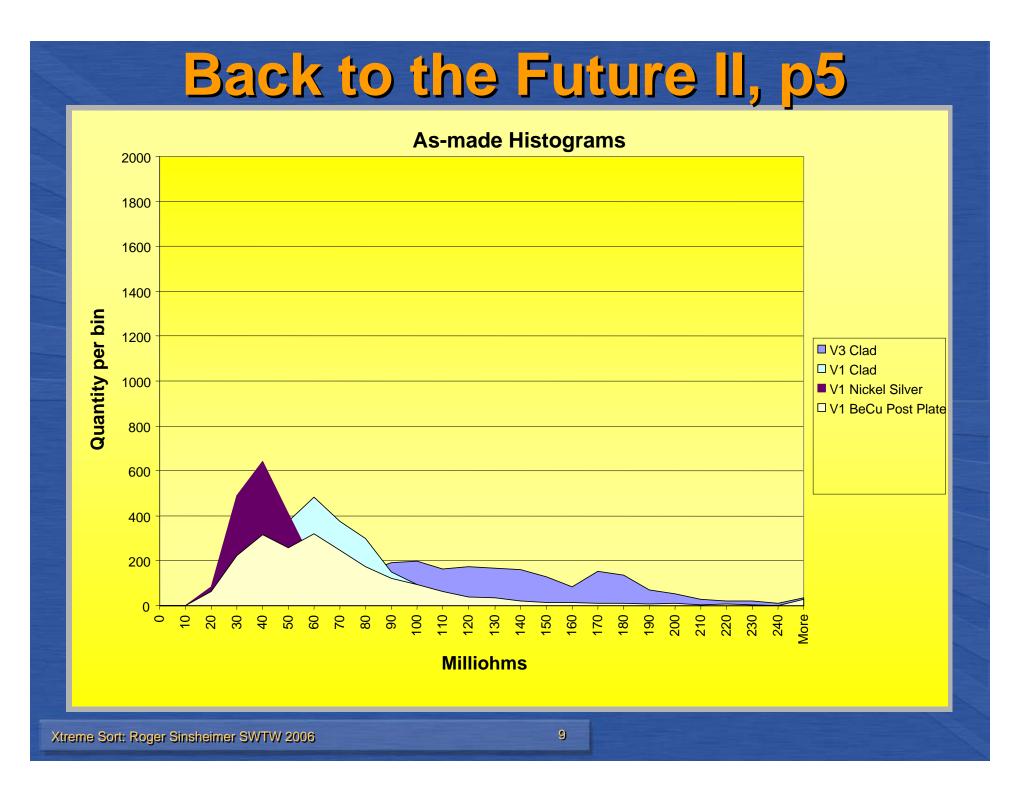


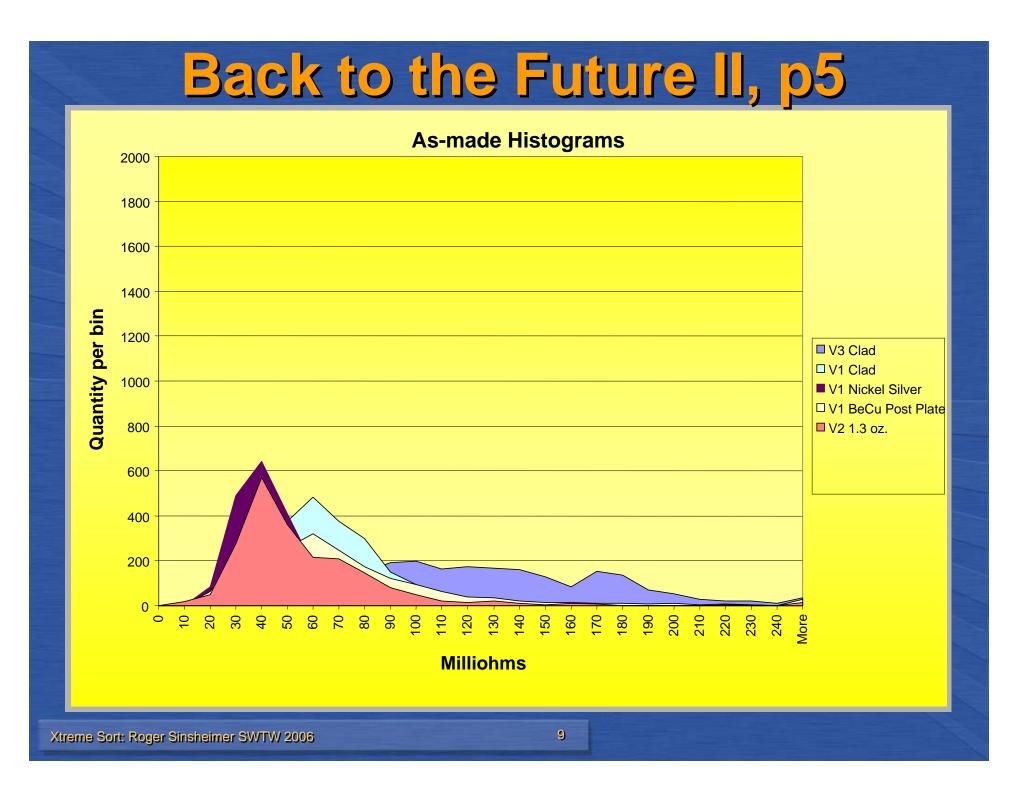


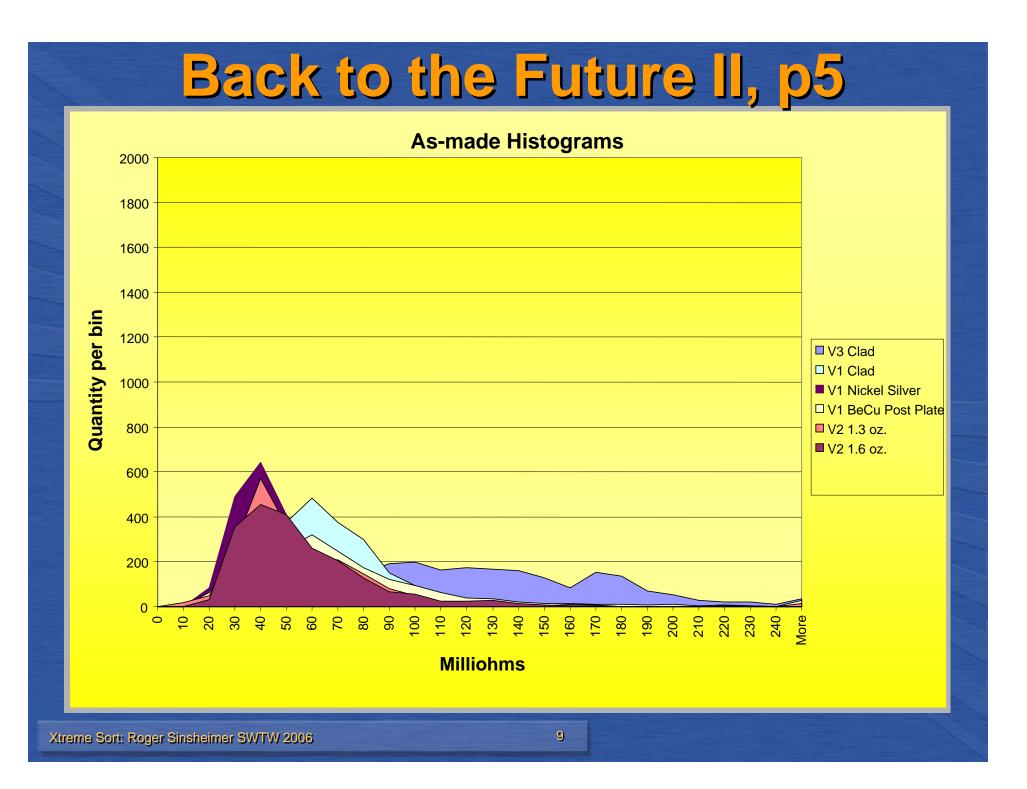


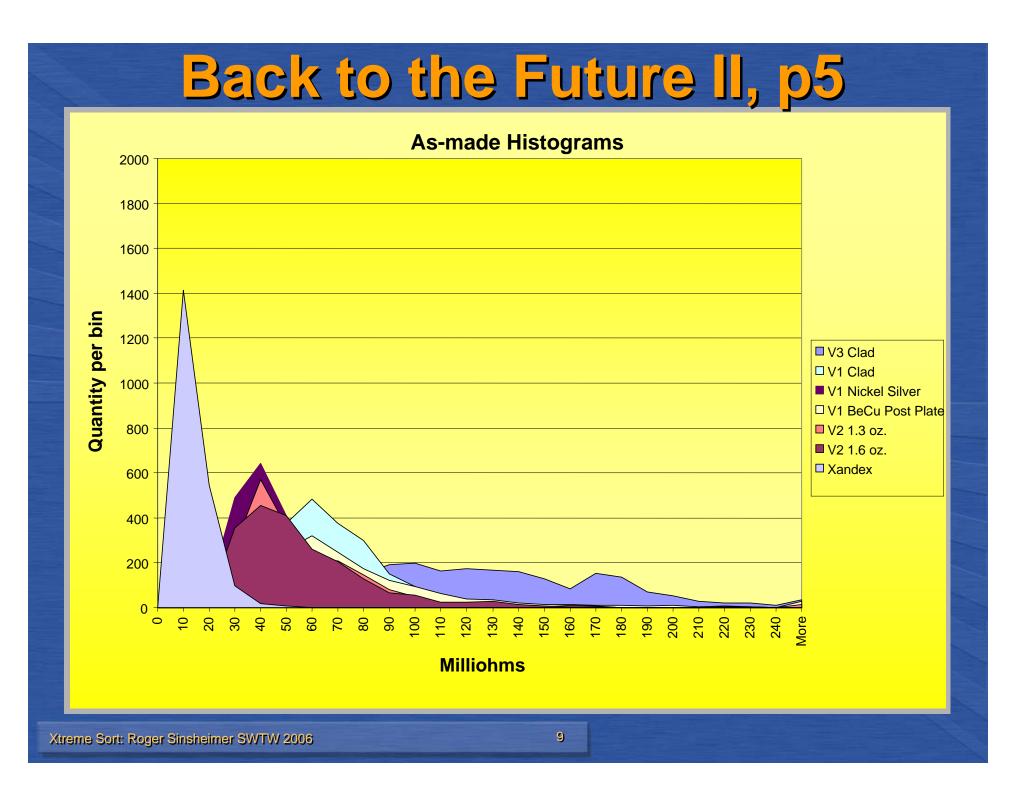


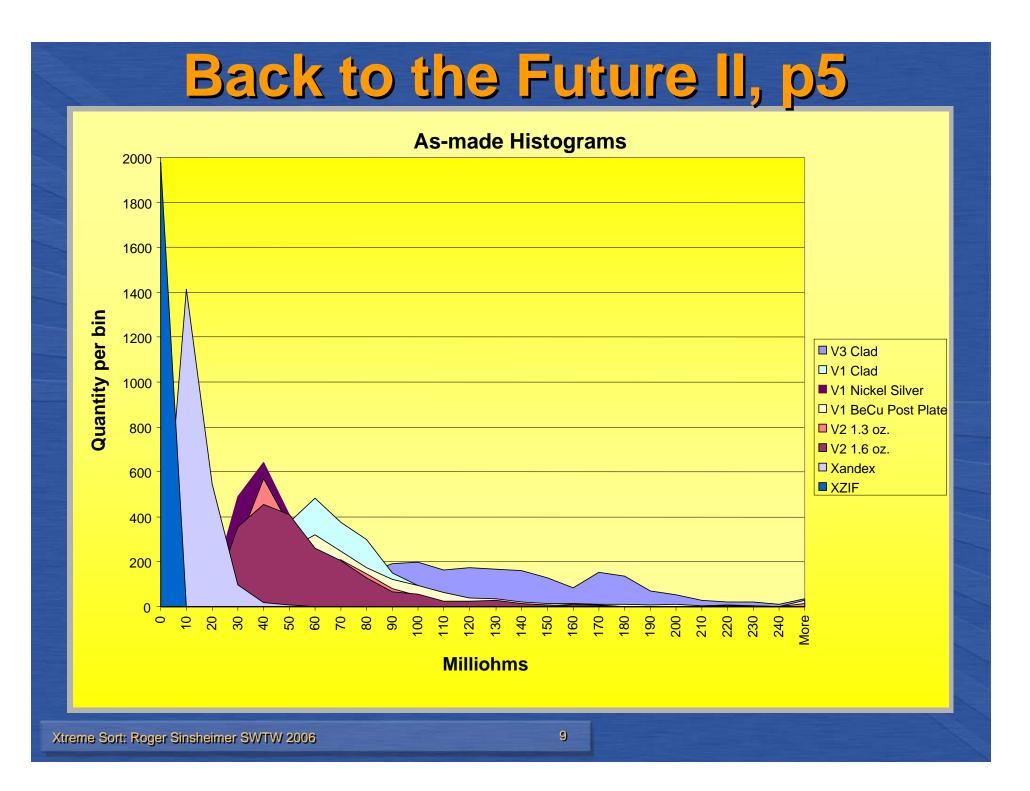


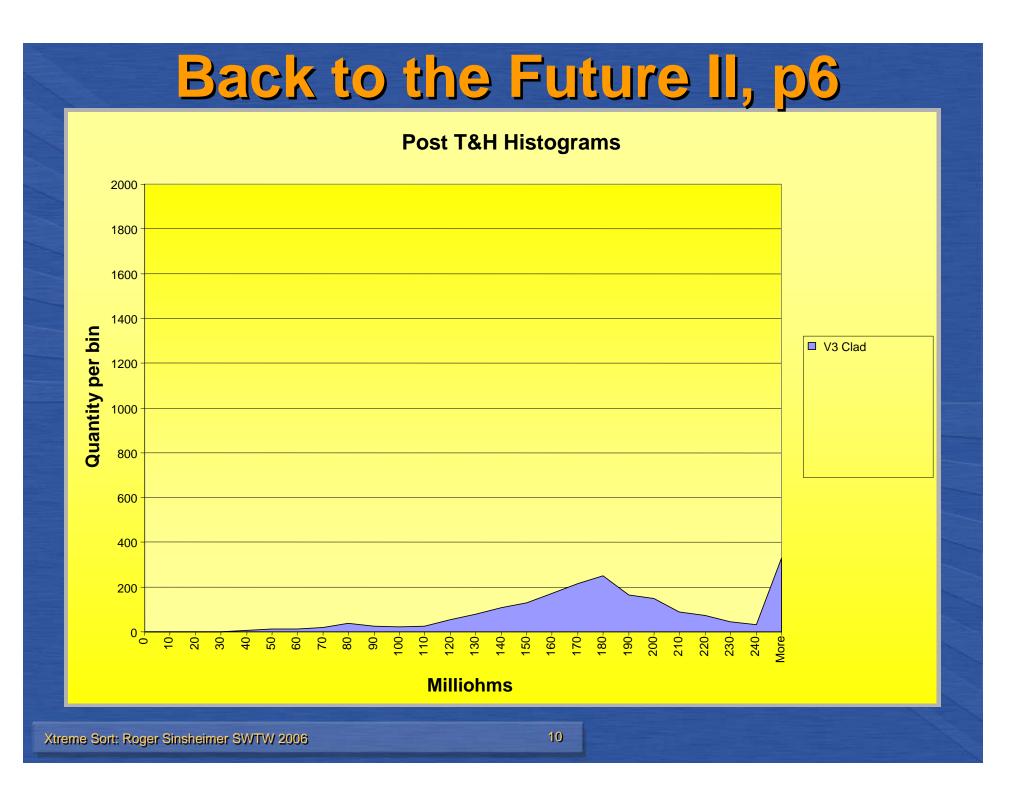


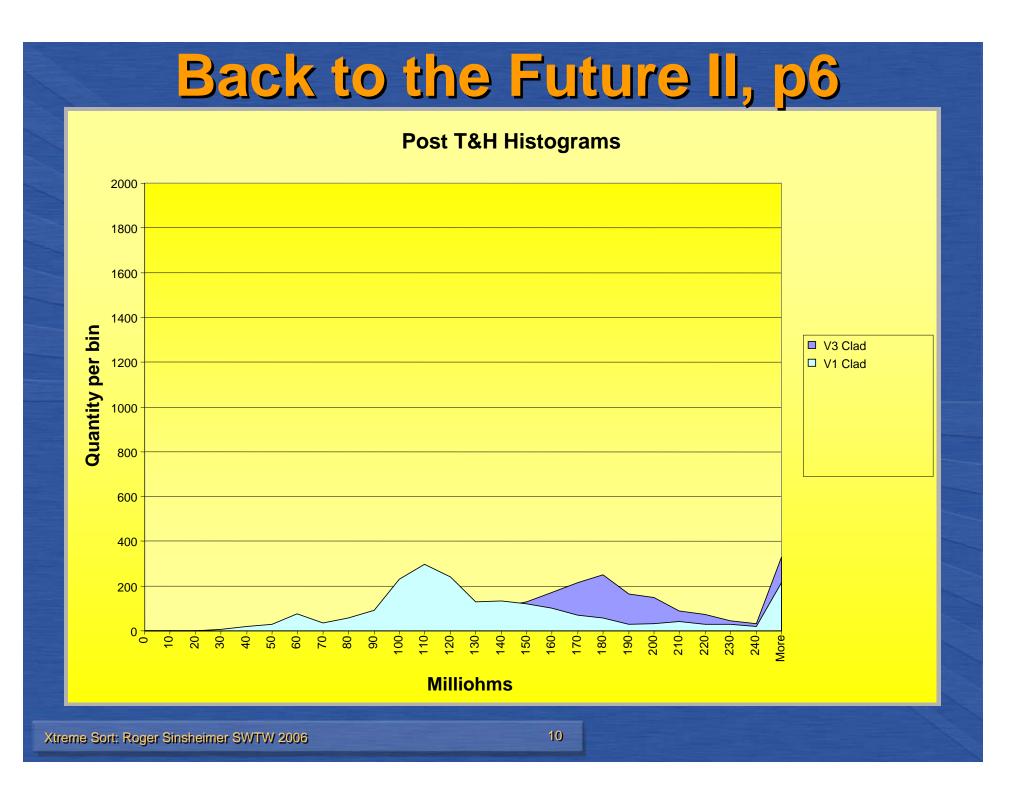


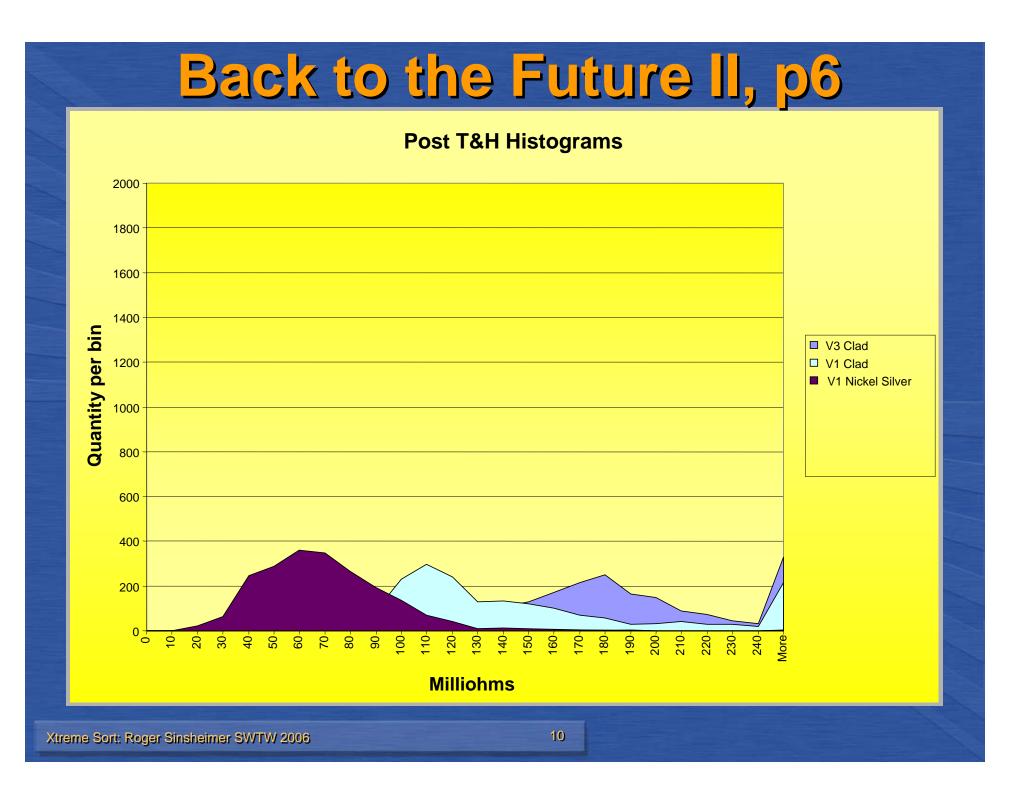


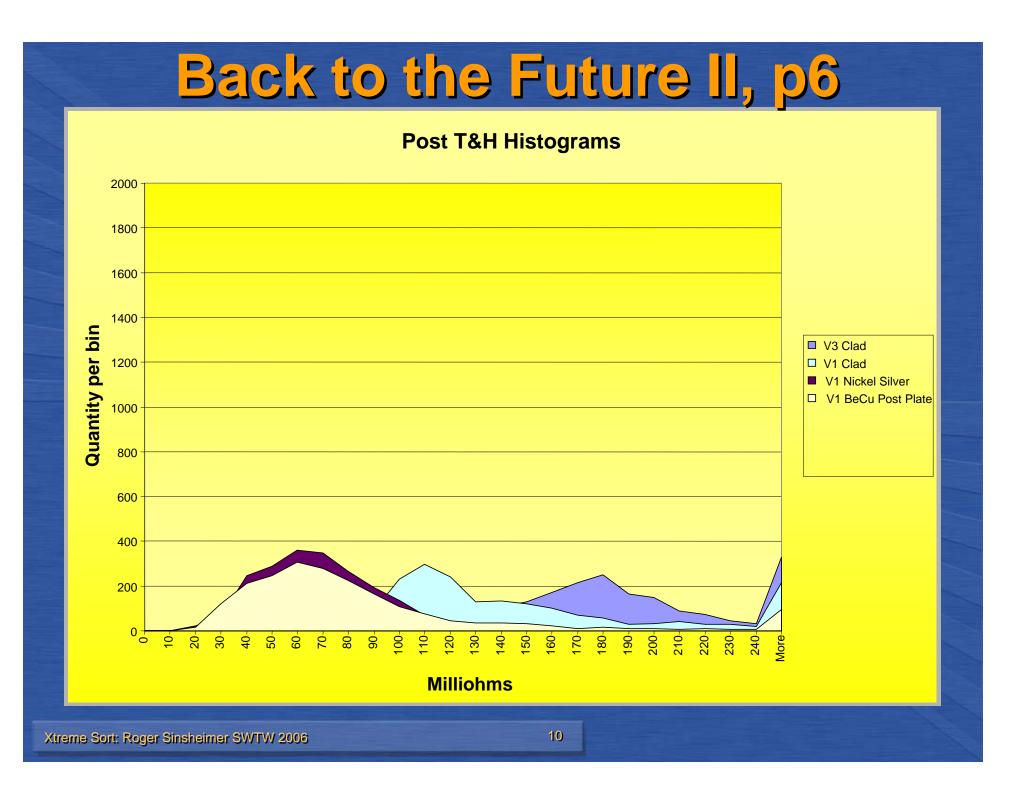


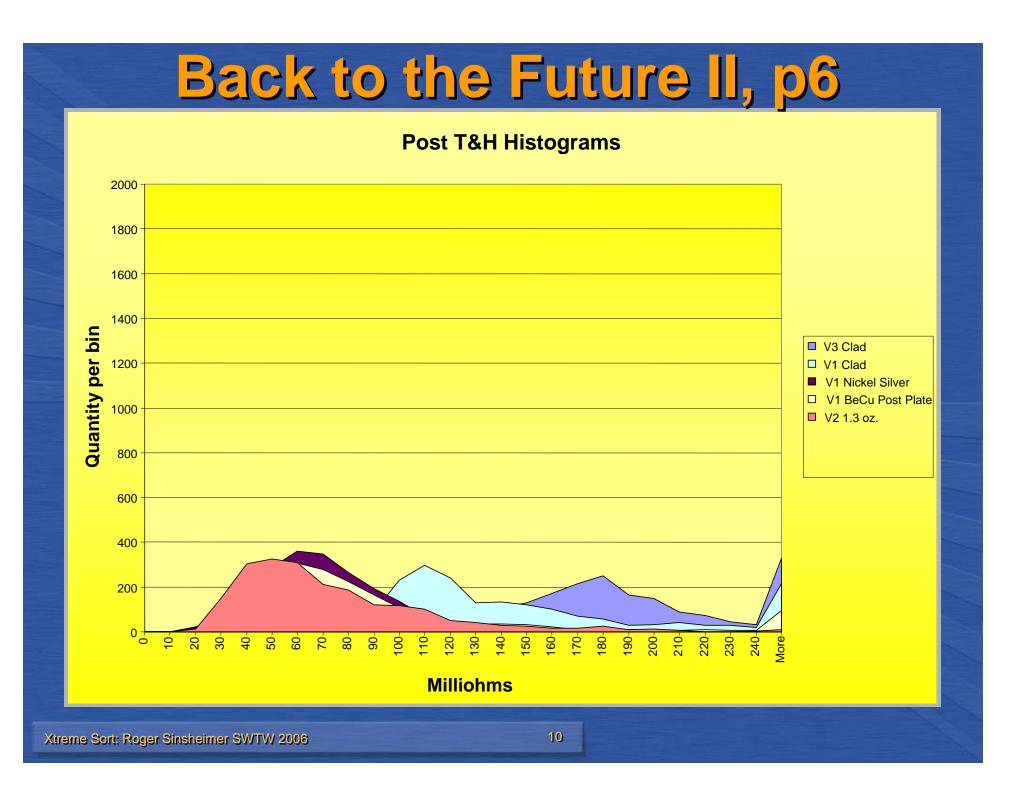


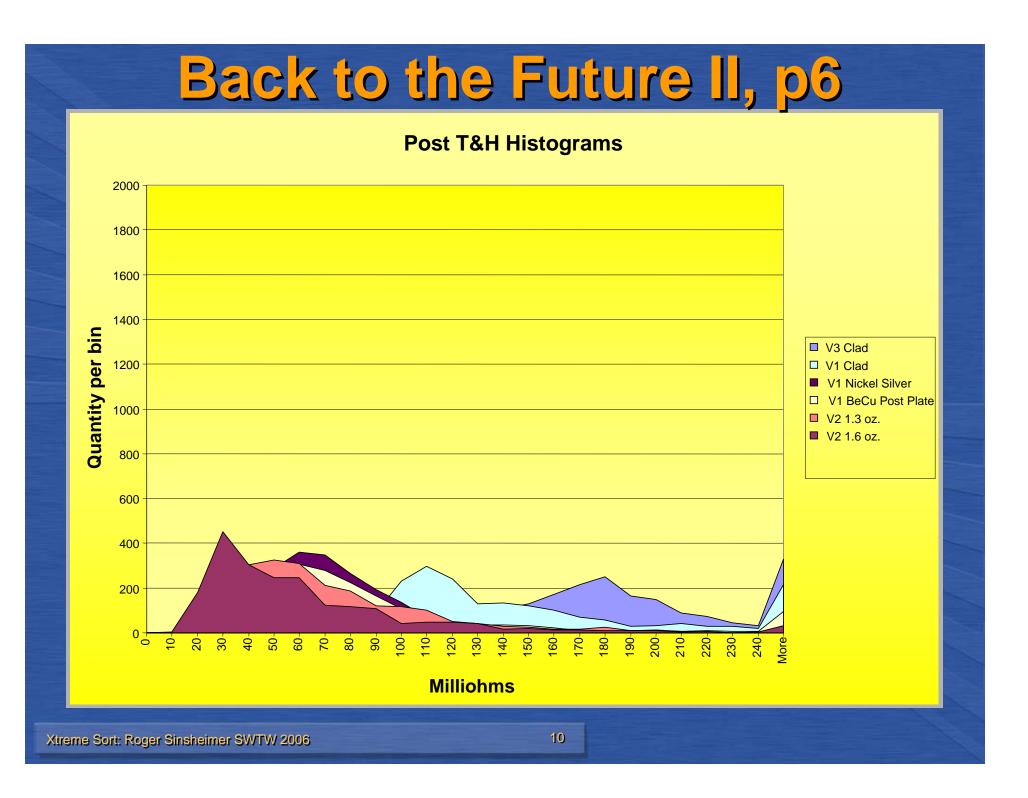


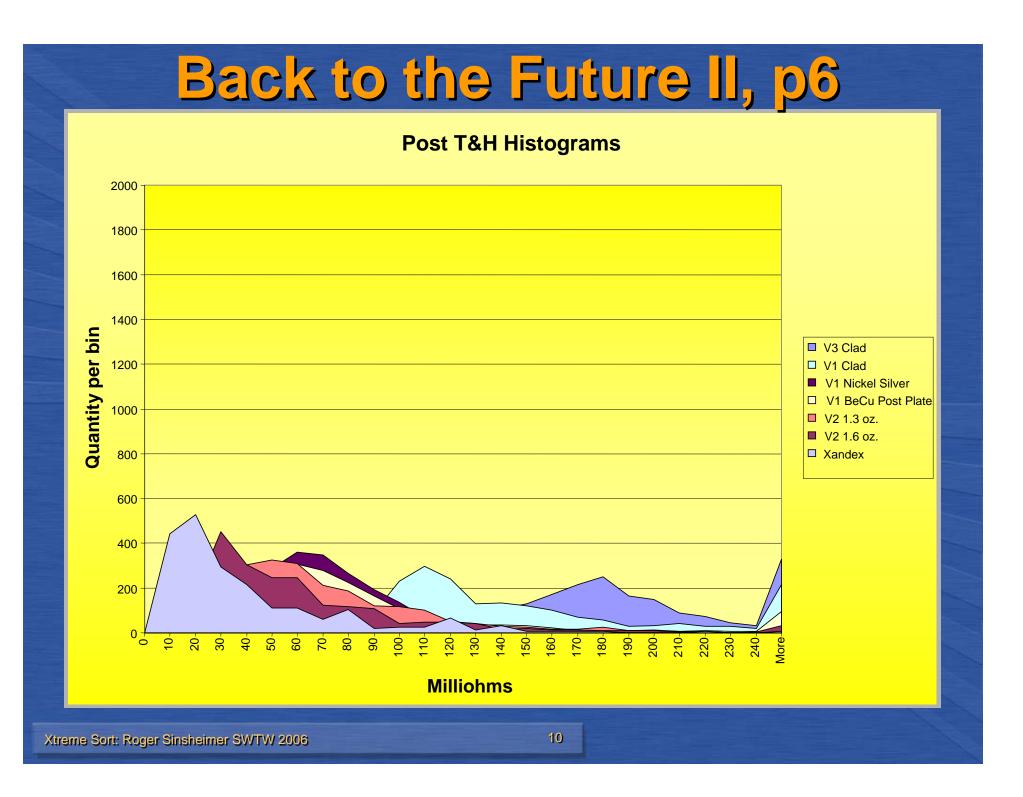


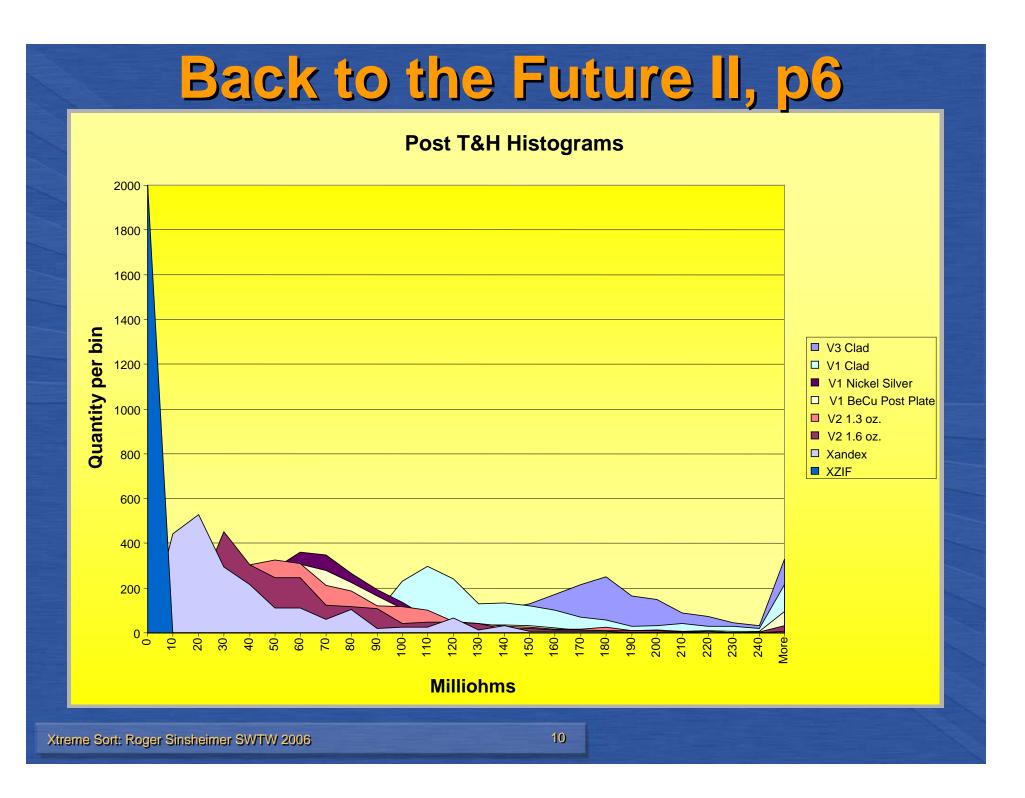






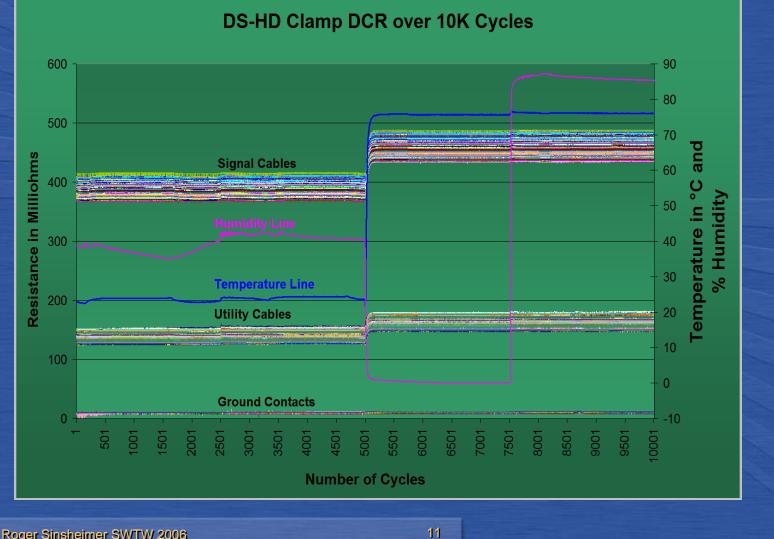






Reliability

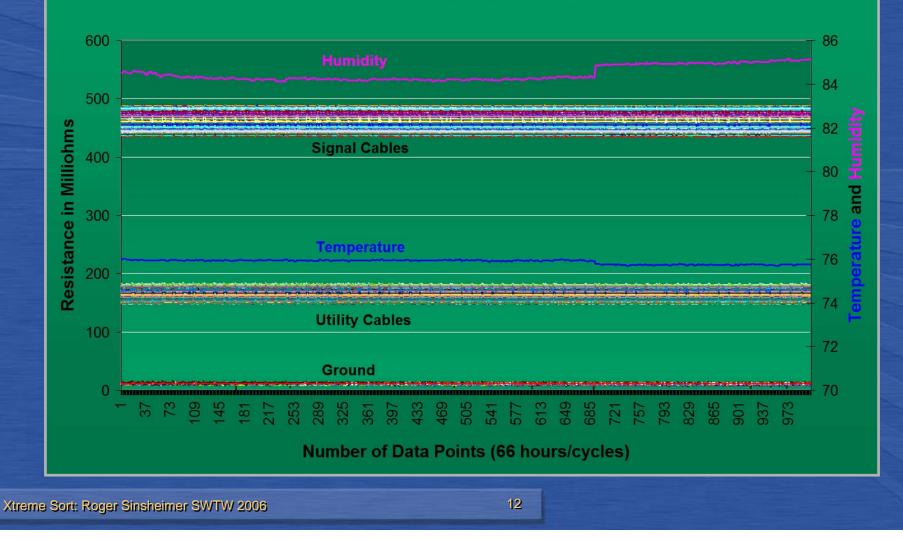
2.5 million XZIF mate / de-mate cycles



Reliability, p2

DS-HD Clamp DCR Test

(5 Minutes Clamped 55 Minutes Open) Temperature 75° Celsius at 85% Relative Humidity



So how did we do this?



Knocked the problem on its ear – turned the signal 90°, delivered 120g of force per contact

So how did we do this?



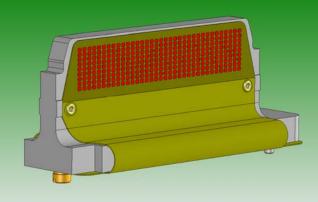
 Knocked the problem on its ear – turned the signal 90°, delivered 120g of force per contact
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So how did we do this?

➔ XZIF

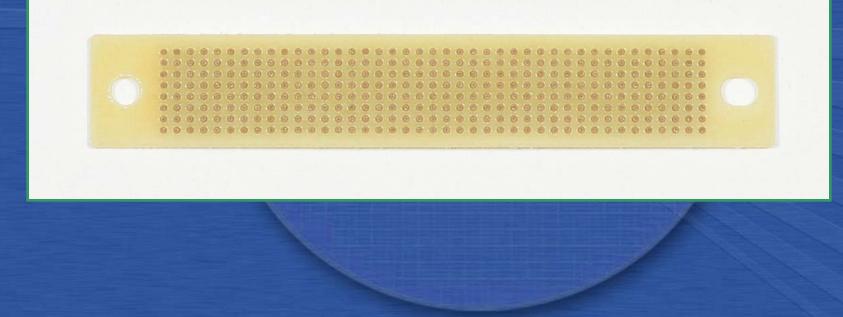
- Knocked the problem on its ear turned the signal 90°, delivered 120g of force per contact
- Co-developed rock-solid contact technology
- Created means for self-alignment between the interconnects

How we did it, p2 Turned the signal 90°

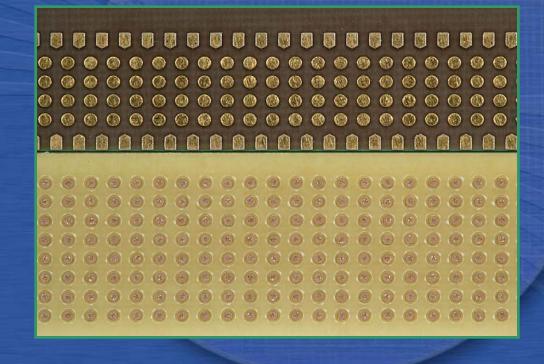




How we clid it, p3Contact technology



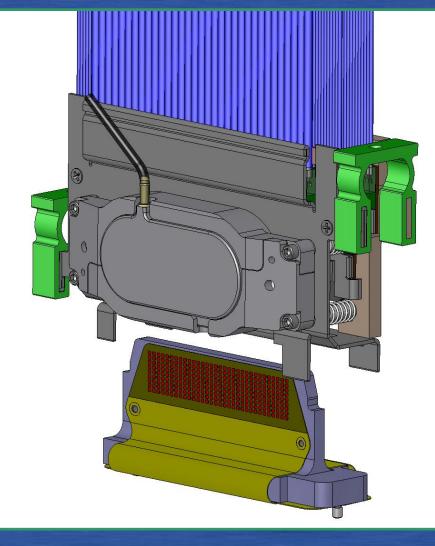
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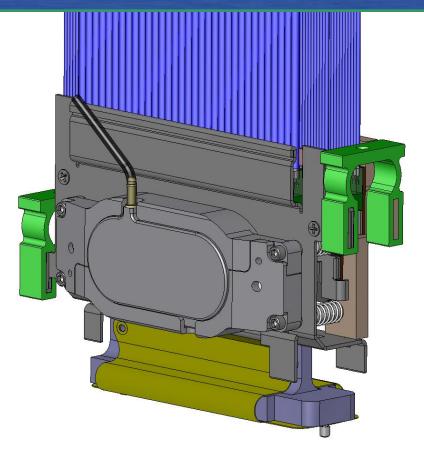


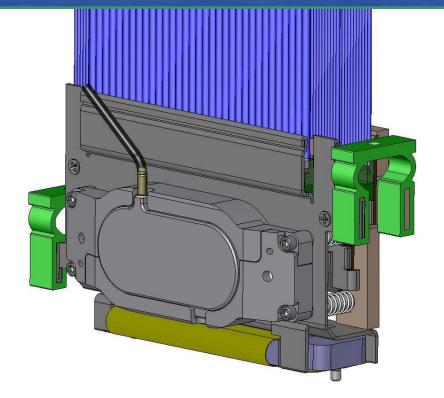
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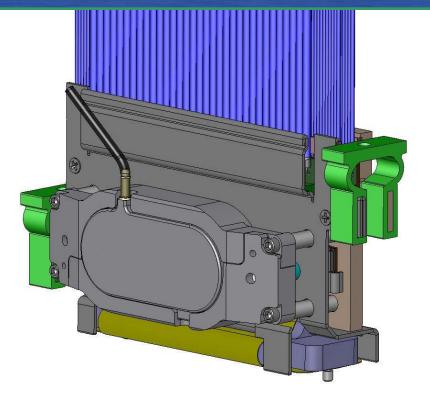
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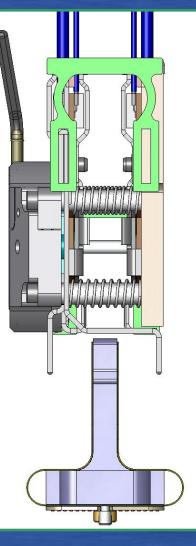


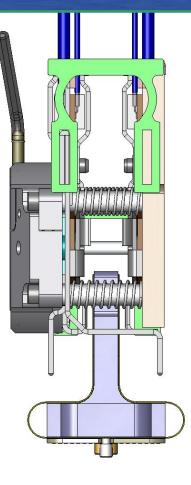


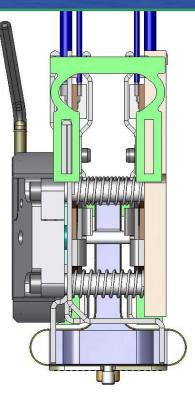


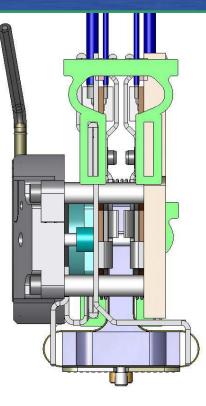


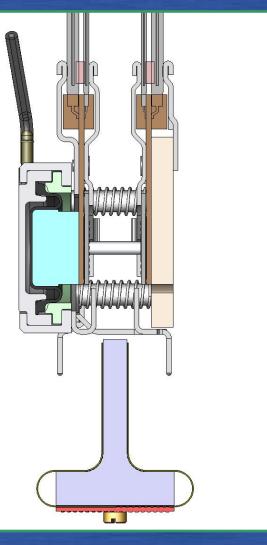


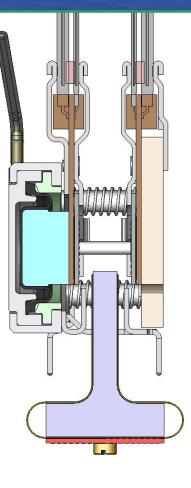


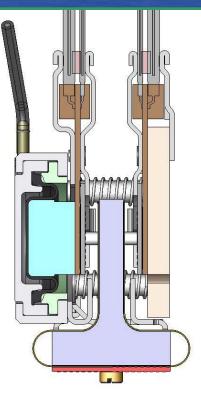


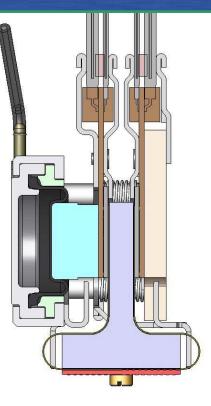


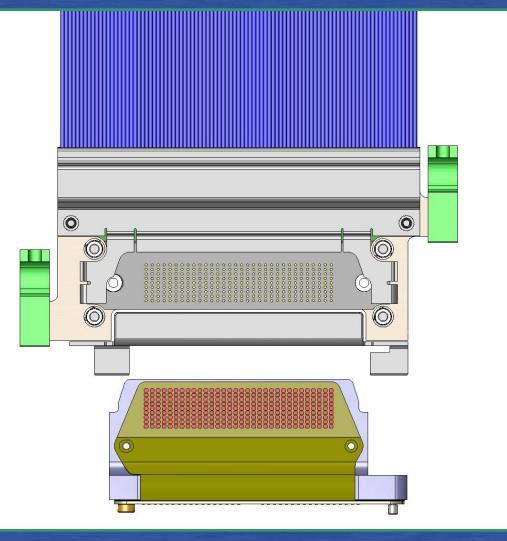


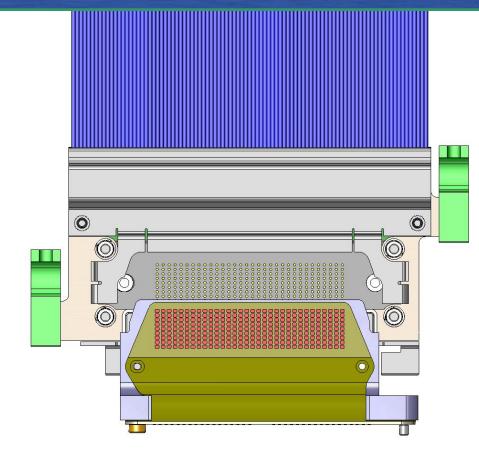


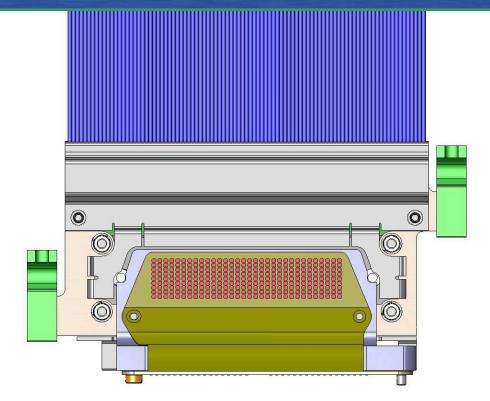












Okay, it's reliable. So what?

Now we've got a reliable interconnect, one that doesn't push on the probe card to create the connections ...

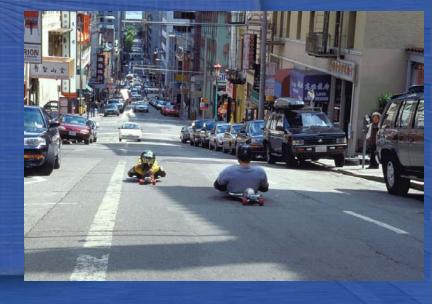
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How about 13,056 (34x384) I/O channels?

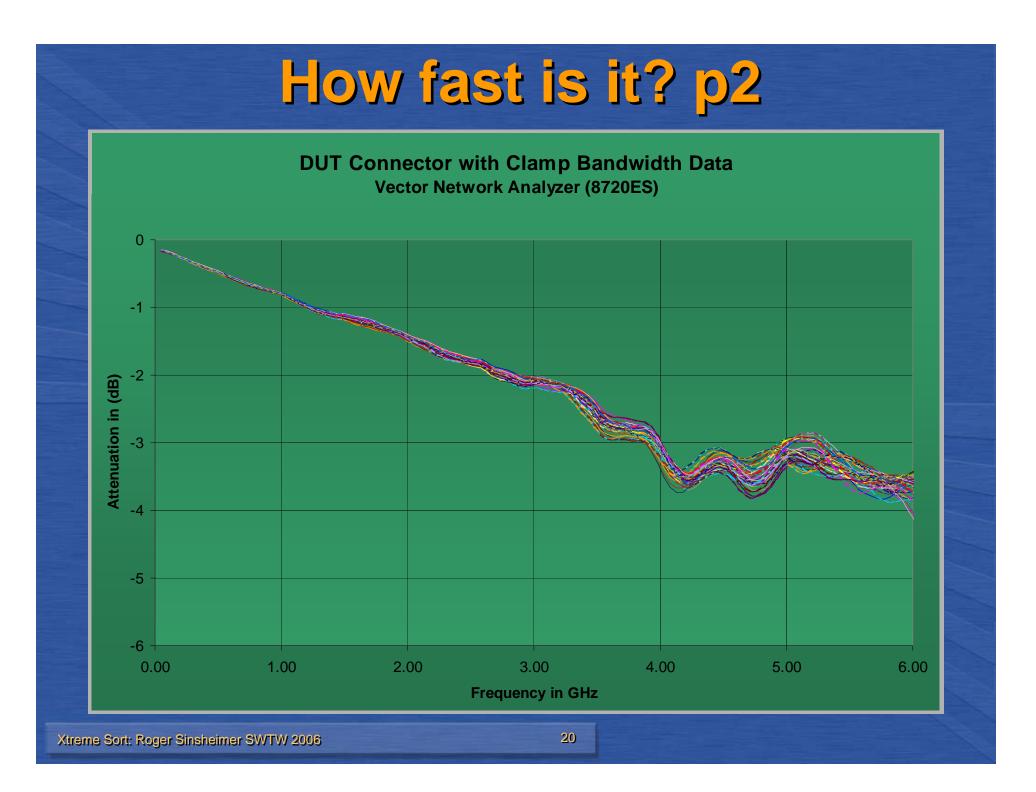
Xtreme Sort



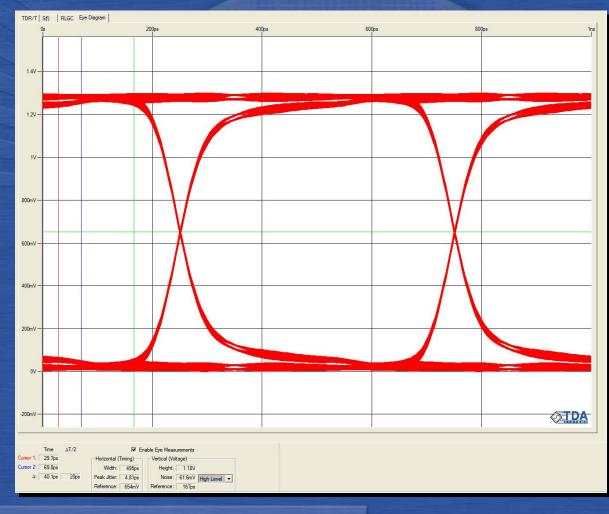


So how fast is it?





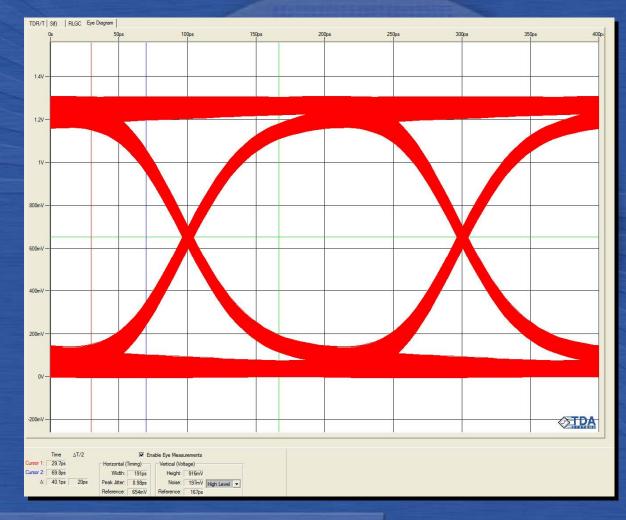
How fast is it? p3 Sequence by the second s



Xtreme Sort: Roger Sinsheimer SWTW 2006

<u>2</u>1

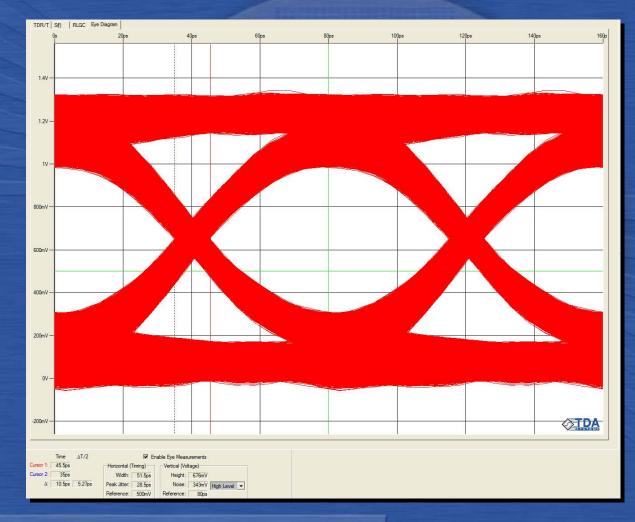
How fast is it? p4 Several Eye diagram – 5 Gb/s



Xtreme Sort: Roger Sinsheimer SWTW 2006

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How fast is it? p5 Sequence to the second sequence of the second second



Xtreme Sort: Roger Sinsheimer SWTW 2006

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Xtreme Sort

Flexible



How we did it, p5 Use boards for the ends, cables for the long stretch



How we did it, p6 Boards and cables are optimized for the application:

How we did it, p6

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 - Air-enhanced Dielectric Coaxial Cable for high speed channels

How we did it, p6

- Boards and cables are optimized for the application:
 - Air-enhanced Dielectric Coaxial Cable for high speed channels
 - Standard Ribbon Cable for Utility channels

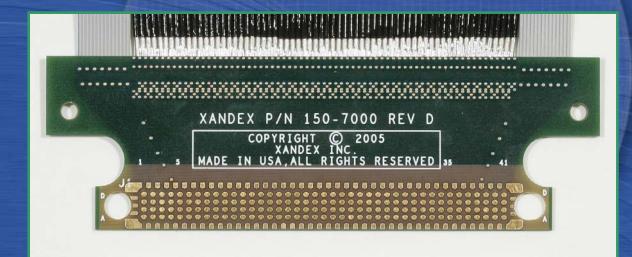
How we did it, p6

- Boards and cables are optimized for the application:
 - Air-enhanced Dielectric Coaxial Cable for high speed channels
 - Standard Ribbon Cable for Utility channels
 - Twisted Pair or "Shieldless Coax" Cable for inexpensive, low speed (<25 MHz) channels</p>

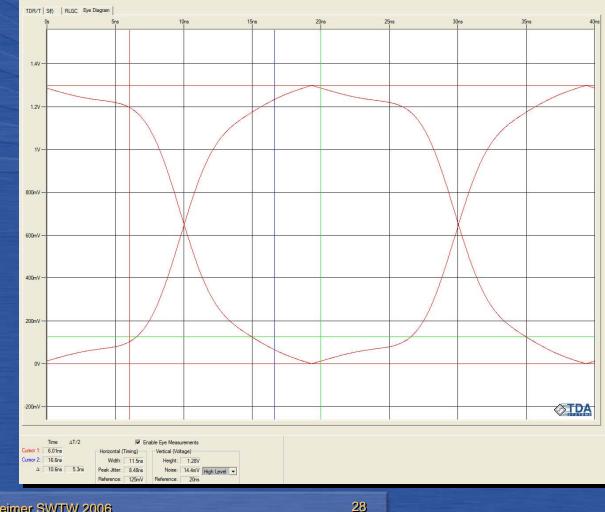
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- Boards and cables are optimized for the application:
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 - Standard Ribbon Cable for Utility channels
 - Twisted Pair or "Shieldless Coax" Cable for inexpensive, low speed (<25 MHz) channels</p>
 - Ultra-low Inductance Coaxial Cable for Power channels

How we did it, p7 Channel requirements can be mixed and matched within a single board / XZIF clamp assembly



How fast is it? p6 Twisted Pair Eye diagram, 50 Mb/s



Got Power?

Power transmission line spec's:
 500 nΩ round-trip DCR
 150 pH Inductance
 35 mΩ Impedance – stable into MHz range

Got Power?

Power transmission line spec's:
 500 nΩ round-trip DCR
 150 pH Inductance
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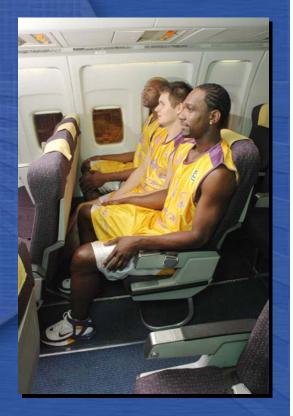
Energy dissipated across the entire path @ 400A load is 30W

Got Power?

Power transmission line spec's:
 500 nΩ round-trip DCR
 150 pH Inductance
 35 mΩ Impedance – stable into MHz range

 Energy dissipated across the entire path @ 400A load is 30W
 Force is carried by >300 contact structures







What about probe card size?

⇒ In 2001 440mm diameter was big

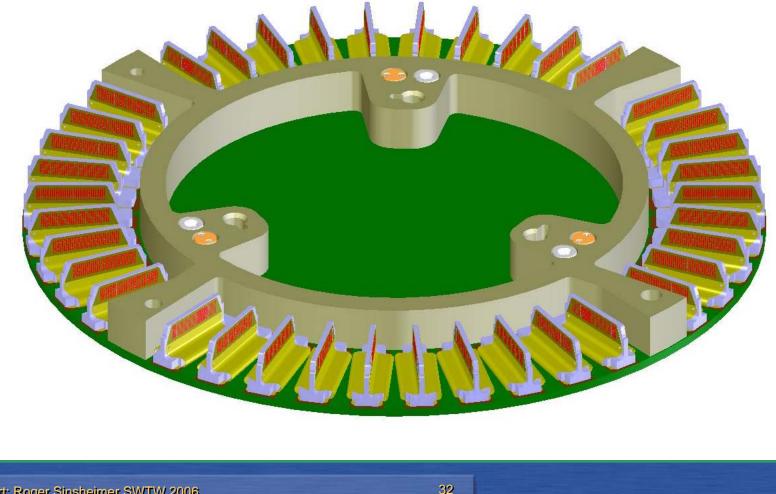
 In 2001 440mm diameter was big
 Design target was to touch down on ¼ of a 200mm wafer – 165mm diameter application space with 2304 I/O was adequate

⇒ In 2001 440mm diameter was big

Design target was to touch down on ¼ of a 200mm wafer – 165mm diameter application space with 2304 I/O was adequate

2006 target is a 300mm single-touch probe card – must have a much bigger application space

Big probe cards are coming 520mm probe card with 320mm app' space



This is a <u>really</u> big probe card

A high pin count 300mm single-touch probe card is estimated to weigh as much as 75 pounds (35 kg)

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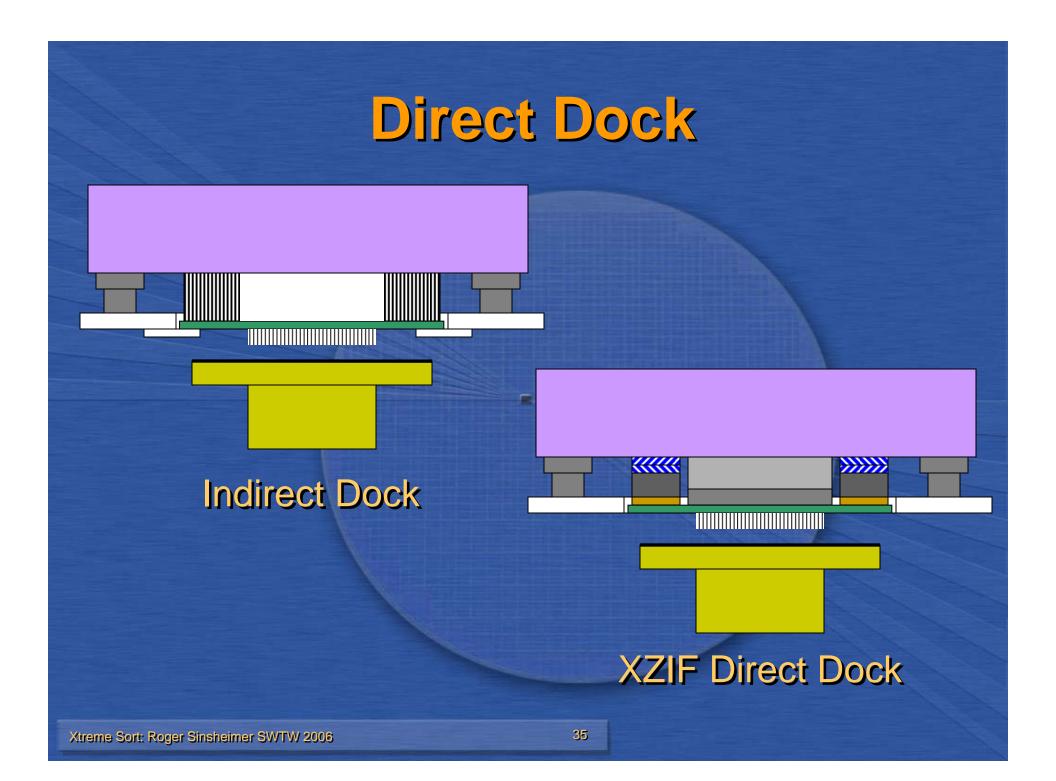
This is a <u>really</u> big probe card A high pin count 300mm single-touch probe card is estimated to weigh as much as 75 pounds (35 kg) It will most likely cost somewhere in excess of US\$150k Would you want to carry this beast around the sort floor in your hands?

This is a <u>really</u> big probe card A high pin count 300mm single-touch probe card is estimated to weigh as much as 75 pounds (35 kg) It will most likely cost somewhere in excess of US\$150k Would you want to carry this beast around the sort floor in your hands? ⇒ I didn't think so.

OHeat Resistant

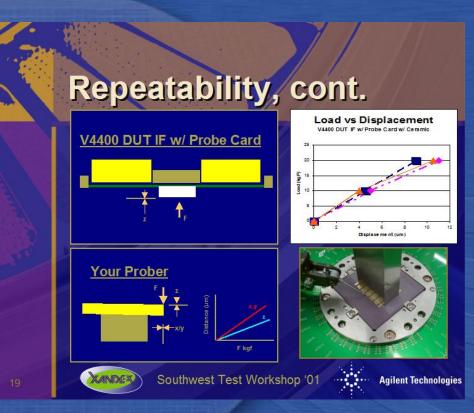






Back to the Future, p2

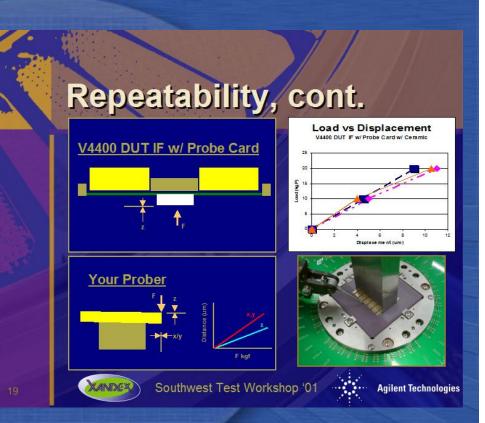
By using Direct Dock, we can make the mechanical support behind the probe card very rigid.



Back to the Future, p2

By using Direct Dock, we can make the mechanical support behind the probe card very rigid.

Thermal isolation of the probe card support dramatically reduces Hot Sort soak time



Direct Dock, p2

Probe Tip Z-axis Motion During Hot Soak









What happens to the prober?

Imagine a 300mm single-touch probe card – 60,000 probe needles, 300 kg (60k x 5g) to compress the probe needles.

What happens to the prober?

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 Wafer chucks don't put out that much force ... today

What happens to the prober?

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 60,000 probe needles, 300 kg (60k x 5g) to compress the probe needles.

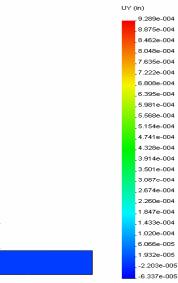
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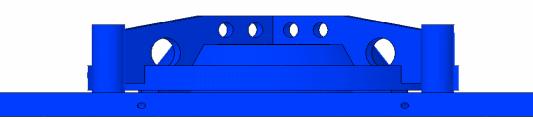
 today

 Prober structure will be working <u>extremely</u> hard.

What happens to the prober? p2

Model name: Top FEA Layout 052206 Study name: Study 1 Plot type: Static displacement Plot1 Deformation scale: 3797.69

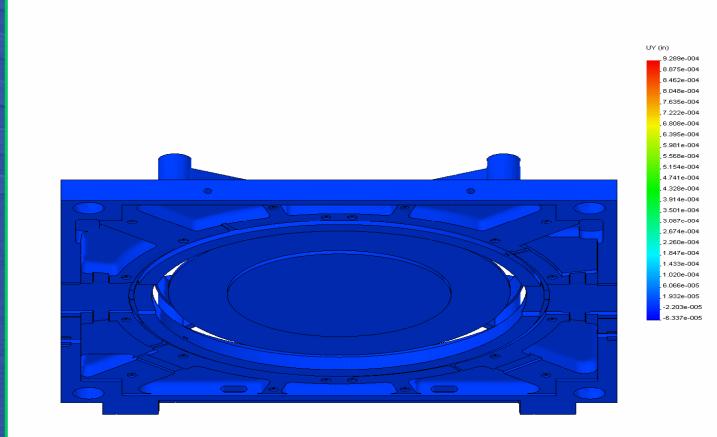




4.741e-004 4.328e-004 1.847e-004 1.433e-004 1.020e-004 6.066e-005

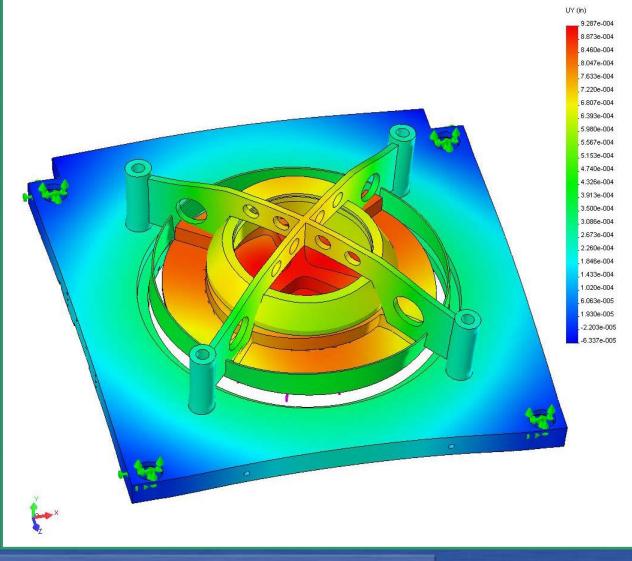
What happens to the prober? p3

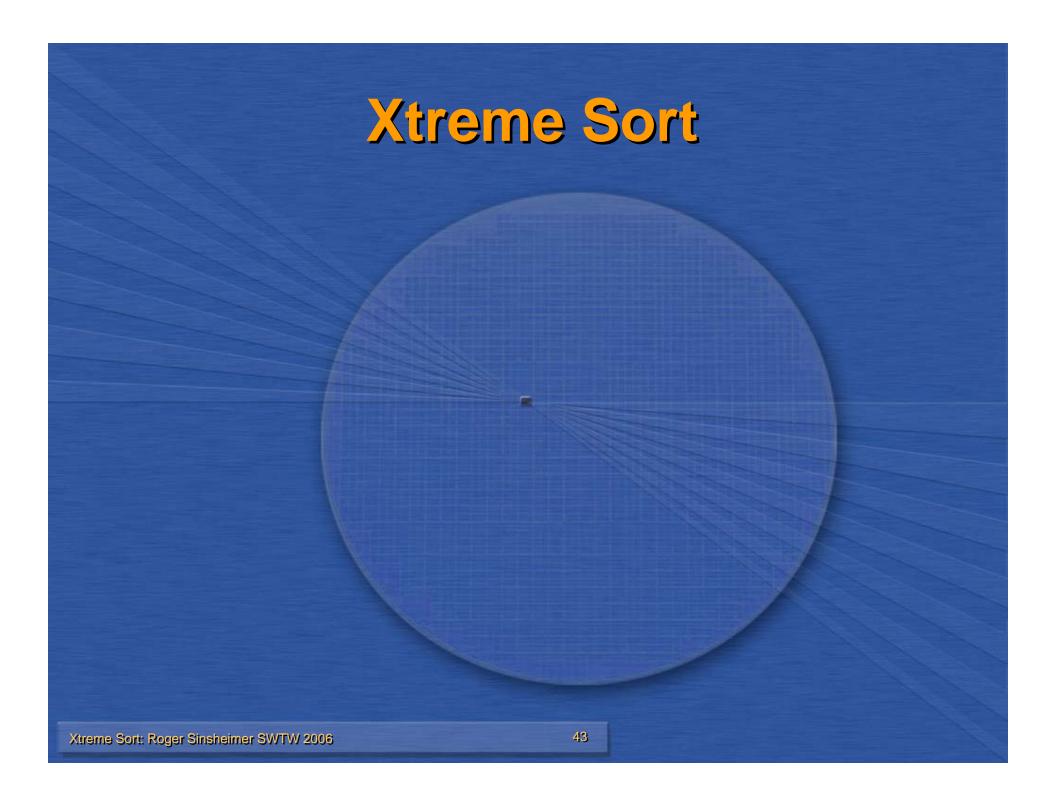
Model name: Top FEA Layout 052206 Study name: Study 1 Plot type: Static displacement Plot1 Deformation scale: 3797.69



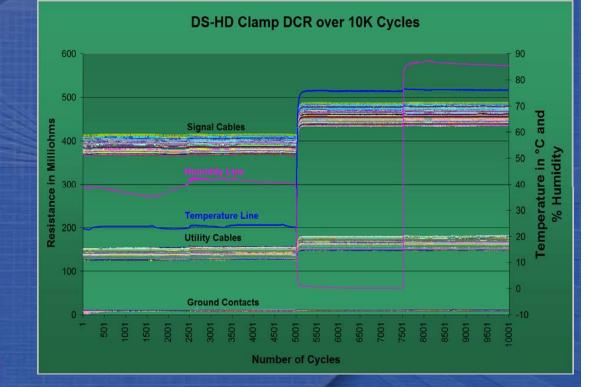
41

What happens to the prober? p4



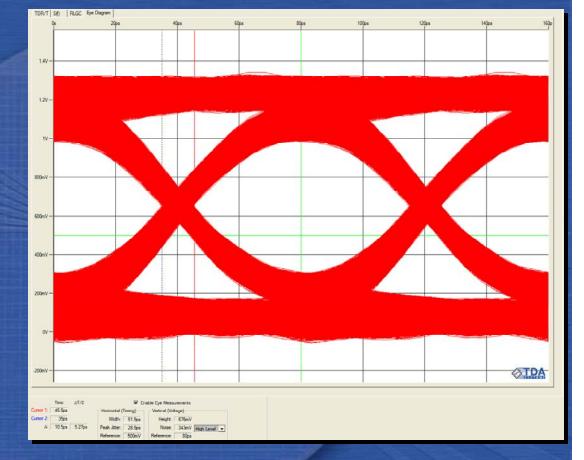


Capabilities: Reliable



Capabilities:

⇒ Fast

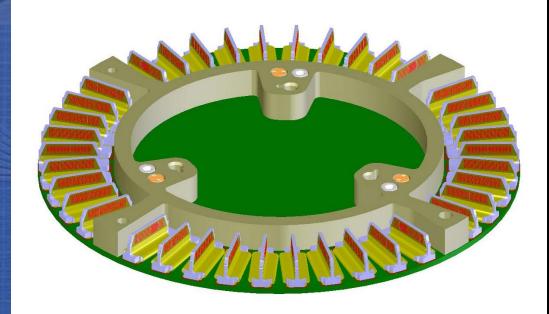


Capabilities:

Flexible

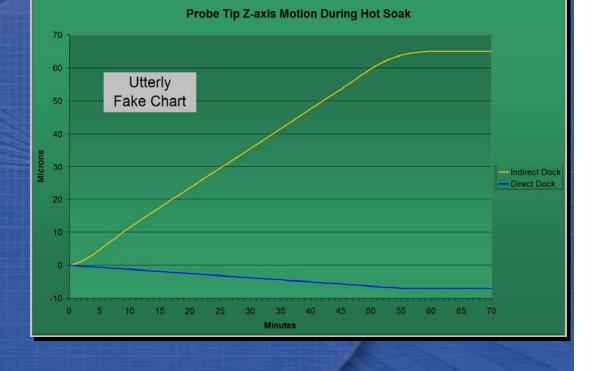


Capabilities:



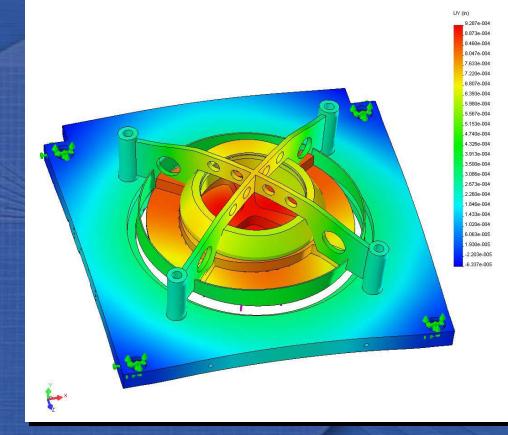


Capabilities:



Heat Resistant

Capabilities:





Credit where credit is most certainly due:

Xandex
 Evan Williams, Staff Mechanical Engineer
 John Wood, Senior Quality Engineer
 Kevin Peebles, Mechanical Engineer
 Tyrus Hudson, Mechanical Engineer